

1988

The first Japan&U.S. Semiconductor Package Joint Committee in Hawaii

~ Packaging ~

Around 1985, engineers of Hitachi and Sharp who developed QFP (Quad Flat Package) for calculator LSI etc. took the leadership, and packaging technology developers of domestic and overseas semiconductor makers gathered together at JEITA (Japan Electronic Industries Association), and they discussed the standardization of QFP outline dimensions. The name of the package, the dimension description system, unification of solder mounting equipment and process conditions on PCB and others were discussed and they were all put together as the package design rule. The design philosophy of the Fixed Body Variable Pin Pitch was followed, and the dimension description was standardized in the international CGS mm unit, replacing MIL standard.

In 1988, as a deliberating body for making the QFP developed in Japan a unified standard with the US manufacturers, Japan-US Semiconductor Package Joint Committee was set up between the JEDEC JC11 Committee of the US and EE13 Committee which was Japan outline committee. The first meeting was held in Hawaii in March of the same year, and the second meeting was held in Asakusa in the following year. The committees were held alternately every year since then.



Picture at the 1st Japan-US Semiconductor Package Joint Committee
In Honolulu

From left to right: Aoki(NEC, representing Japan), Murakami(Hitachi), Shiobasaki(EIAJ), Nixsen(representing US), and committee members from US